

Embedded System Hardware - Processing -

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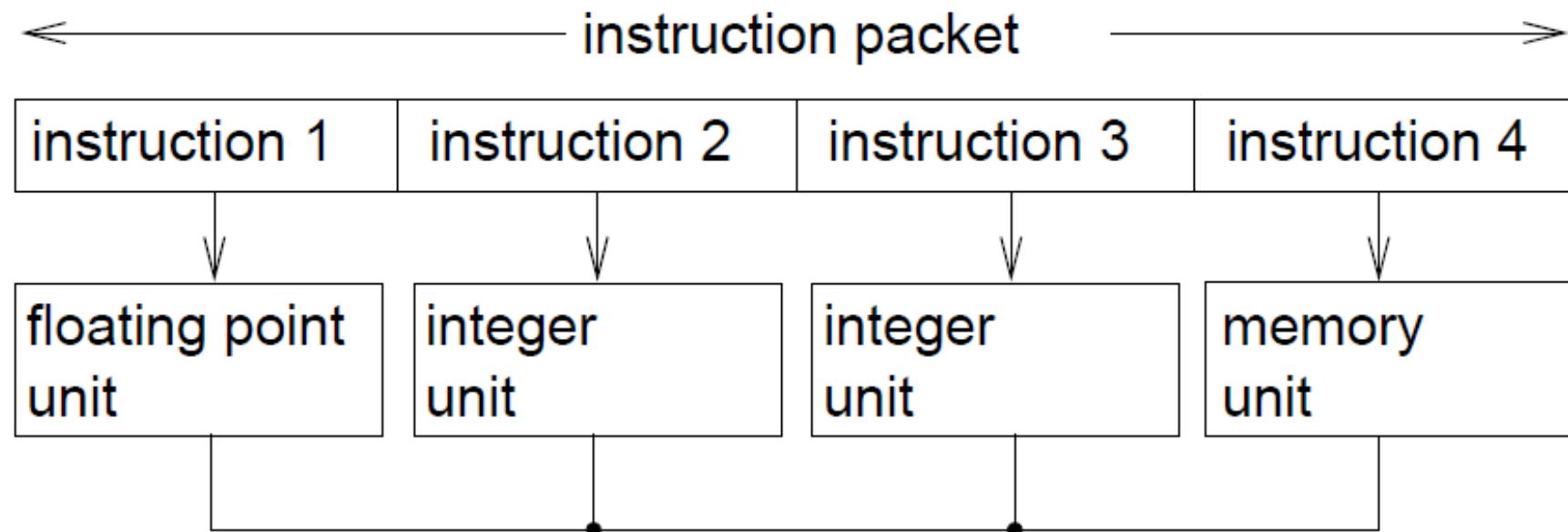
2010年 11月 15日



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Key idea of very long instruction word (VLIW) computers

Instructions included in long instruction packets.
Instruction packets are assumed to be executed in parallel.
Fixed association of packet bits with functional units.



Very long instruction word (VLIW) architectures

- Very long instruction word (“instruction packet”) contains several instructions, all of which are assumed to be executed in parallel.
 - Compiler is assumed to generate these “parallel” packets
 - Complexity of finding parallelism is moved from the hardware (RISC/CISC processors) to the compiler; Ideally, this avoids the overhead (silicon, energy, ..) of identifying parallelism at run-time.
- 👉 A lot of expectations into VLIW machines
- Explicitly parallel instruction set computers (EPICs) are an extension of VLIW architectures: parallelism detected by compiler, but no need to encode parallelism in 1 word.

EPIC: TMS 320C6xx as an example

Bit in each instruction encodes end of parallel execution

31 0 31 0 31 0 31 0 31 0 31 0



Instr. Instr. Instr. Instr. Instr. Instr. Instr.
A B C D E F G

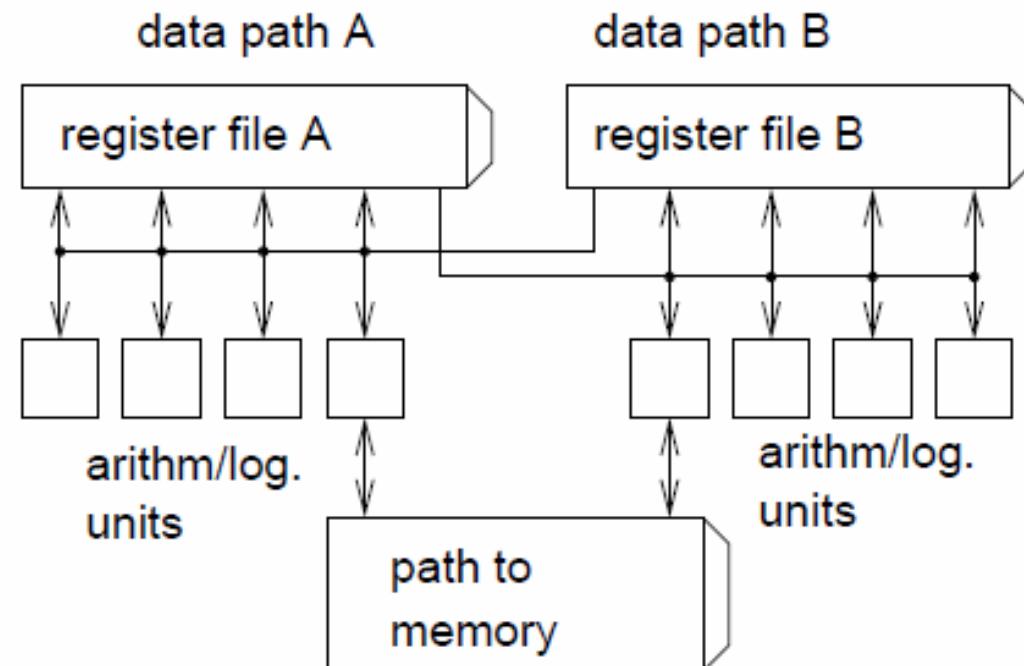
Cycle	Instruction			
1	A			
2	B	C	D	
3	E	F	G	

Instructions B, C and D use disjoint functional units, cross paths and other data path resources. The same is also true for E, F and G.

Parallel execution cannot span several packets.

Partitioned register files

- Many memory ports are required to supply enough operands per cycle.
- Memories with many ports are expensive.
- ☞ Registers are partitioned into (typically 2) sets,
e.g. for TI C60x:



More encoding flexibility with IA-64 Itanium

3 instructions per **bundle**:

127	instruc 1	instruc 2	instruc 3	0
	instruc 1	instruc 2	instruc 3	template

There are 5 instruction types:

- A: common ALU instructions
- I: more special integer instructions (e.g. shifts)
- M: Memory instructions
- F: floating point instructions
- B: branches

*Instruction
grouping
information*

The following combinations can be encoded in templates:

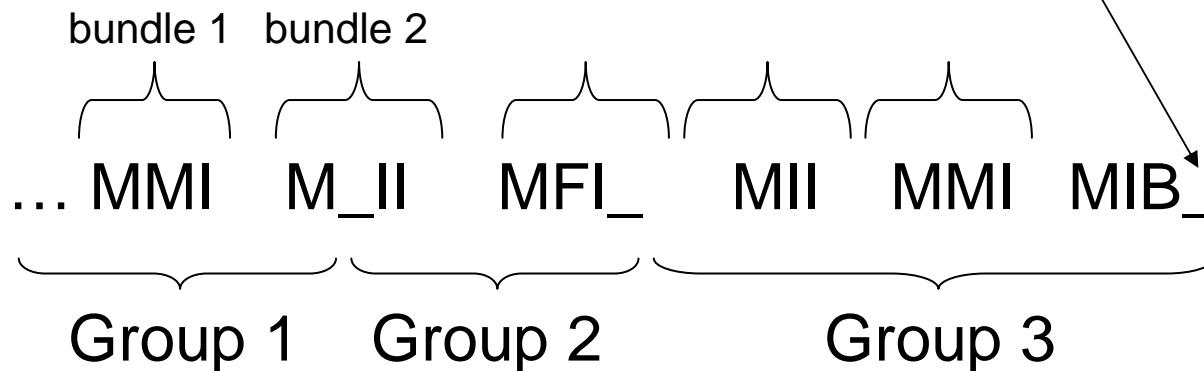
- MII, MMI, MFI, MIB, MMB, MFB, MMF, MBB, BBB, MLX
with LX = *move 64-bit immediate* encoded in 2 slots

Templates and instruction types

End of parallel execution called **stops**.

Stops are denoted by underscores.

Example:



Very restricted placement of stops within bundle.
Parallel execution within groups possible.
Parallel execution can span several bundles

Instruction types are mapped to functional unit types

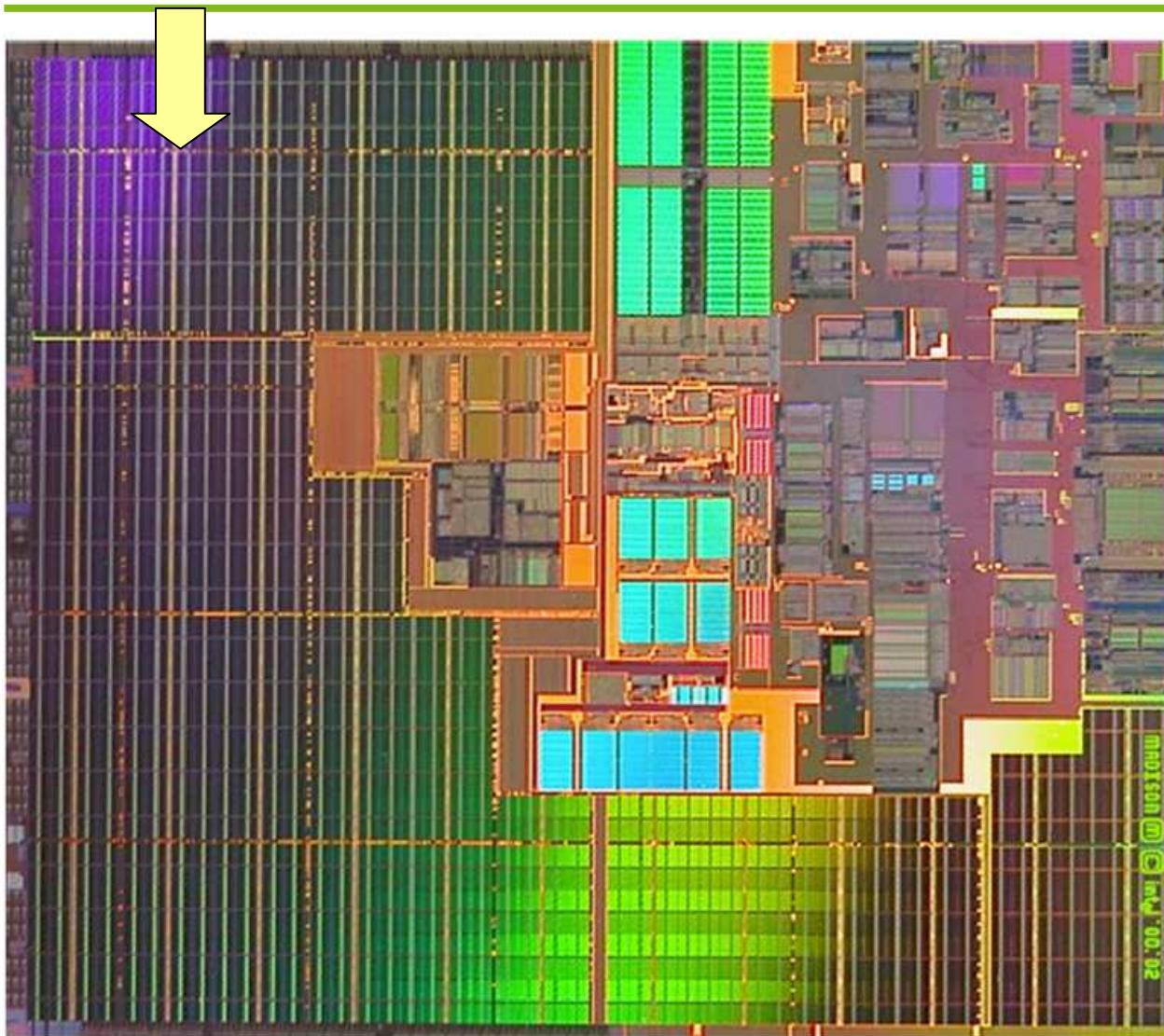
There are 4 functional unit (FU) types:

- M: Memory Unit
- I: Integer Unit
- F: Floating-Point Unit
- B: Branch Unit

Instruction types → corresponding FU type,
except type A (mapping to either I or M-functional units).

L3 cache

Implementation: Itanium 2 (2003)



- 410M transistors
- 374 mm² die size
- 6MB on-die L3 cache
- 1.5 GHz at 1.3V

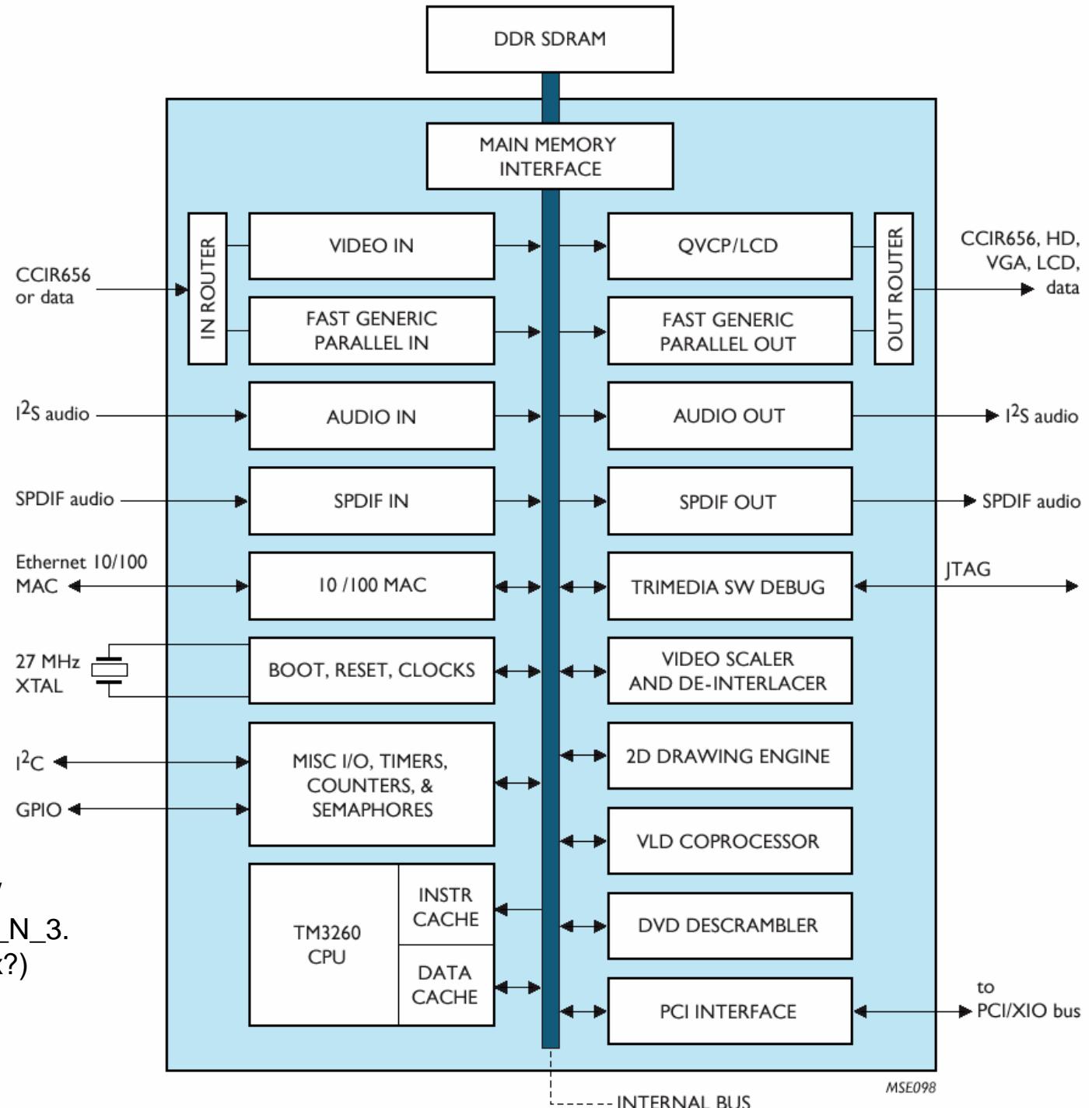
[ftp://download.intel.com/design/itanium2/download/madison_slides_r1.pdf]

Philips TriMedia- Processor

For
multimedia-
applications,
up to 5
instructions/
cycle.

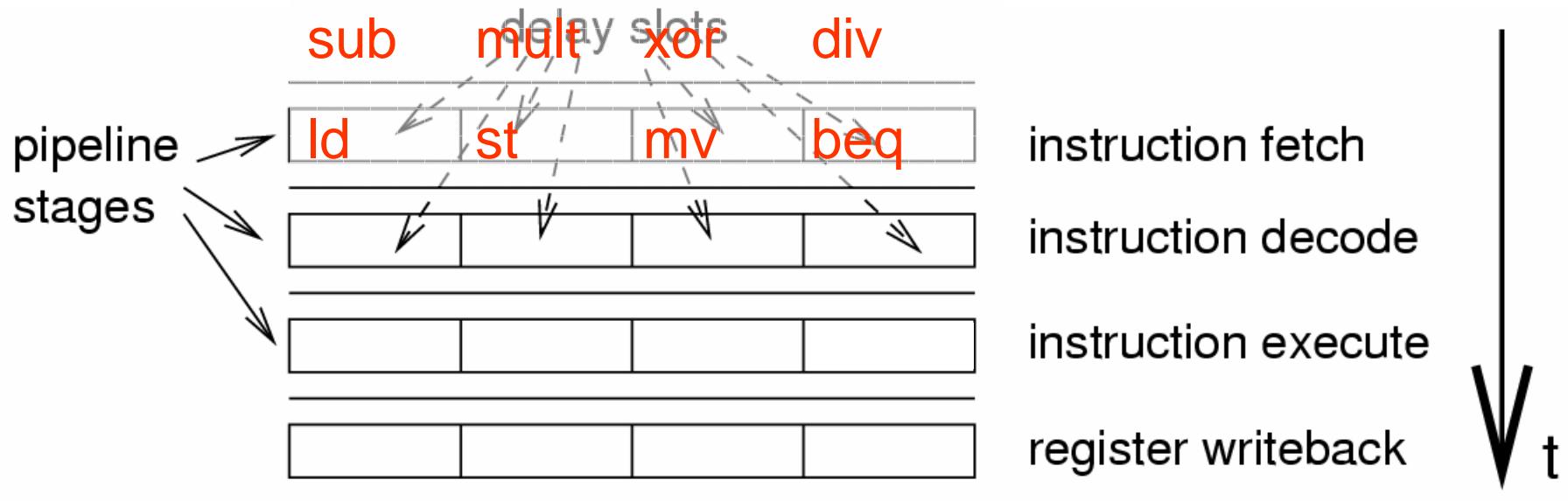
http://www.nxp.com/acrobat/datasheets/PNX15XX_SER_N_3.pdf (incompatible with firefox?)

© NXP



Large # of delay slots, a problem of VLIW processors

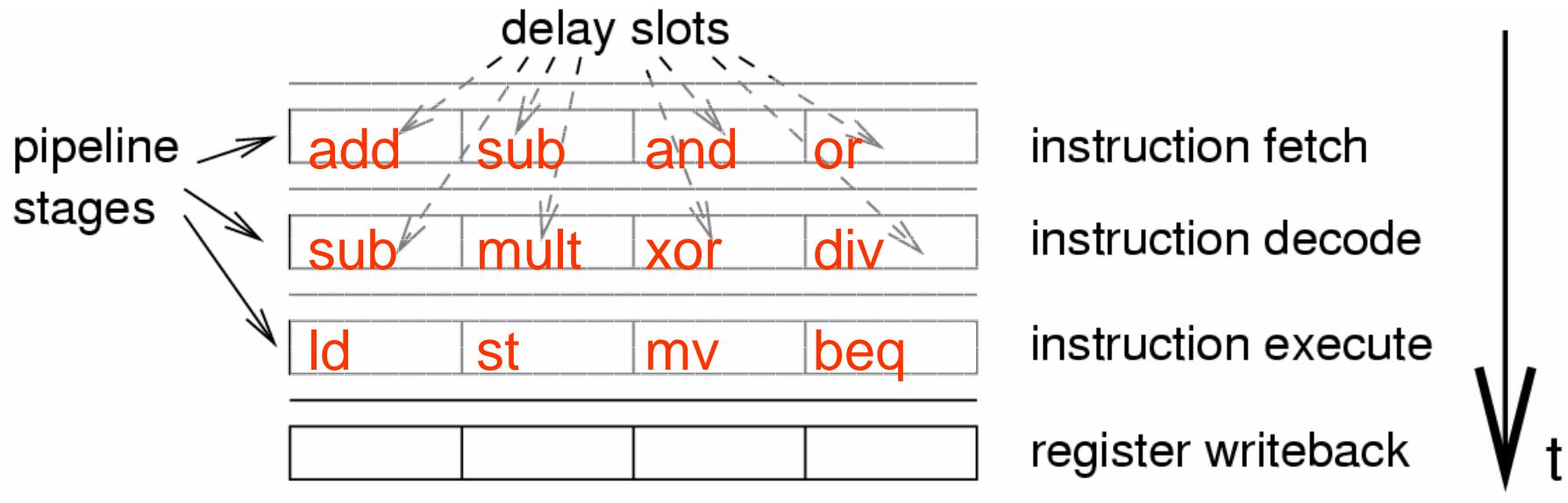
add sub and or



Large # of delay slots, a problem of VLIW processors



Large # of delay slots, a problem of VLIW processors



The execution of many instructions has been started before it is realized that a branch was required.

Nullifying those instructions would waste compute power

- ☞ Executing those instructions is declared a feature, not a bug.
- ☞ How to fill all “delay slots” with useful instructions?
- ☞ Avoid branches wherever possible.

Predicated execution: Implementing IF-statements “branch-free”

Conditional Instruction “[c] I“ consists of:

- **condition c**
- **instruction I**

c = true => I executed
c = false => NOP

Predicated execution: Implementing IF-statements “branch-free“: TI C6x

```
if (c)
{ a = x + y;
  b = x + z;
}
else
{ a = x - y;
  b = x - z;
}
```

Conditional branch

```
[c] B L1
      NOP 5
      B L2
      NOP 4
      SUB x,y,a
      || SUB x,z,b
L1:   ADD x,y,a
      || ADD x,z,b
L2:
```

max. 12 cycles

Predicated execution

```
[c] ADD x,y,a
|| [c] ADD x,z,b
|| [!c] SUB x,y,a
|| [!c] SUB x,z,b
```

1 cycle

Microcontrollers

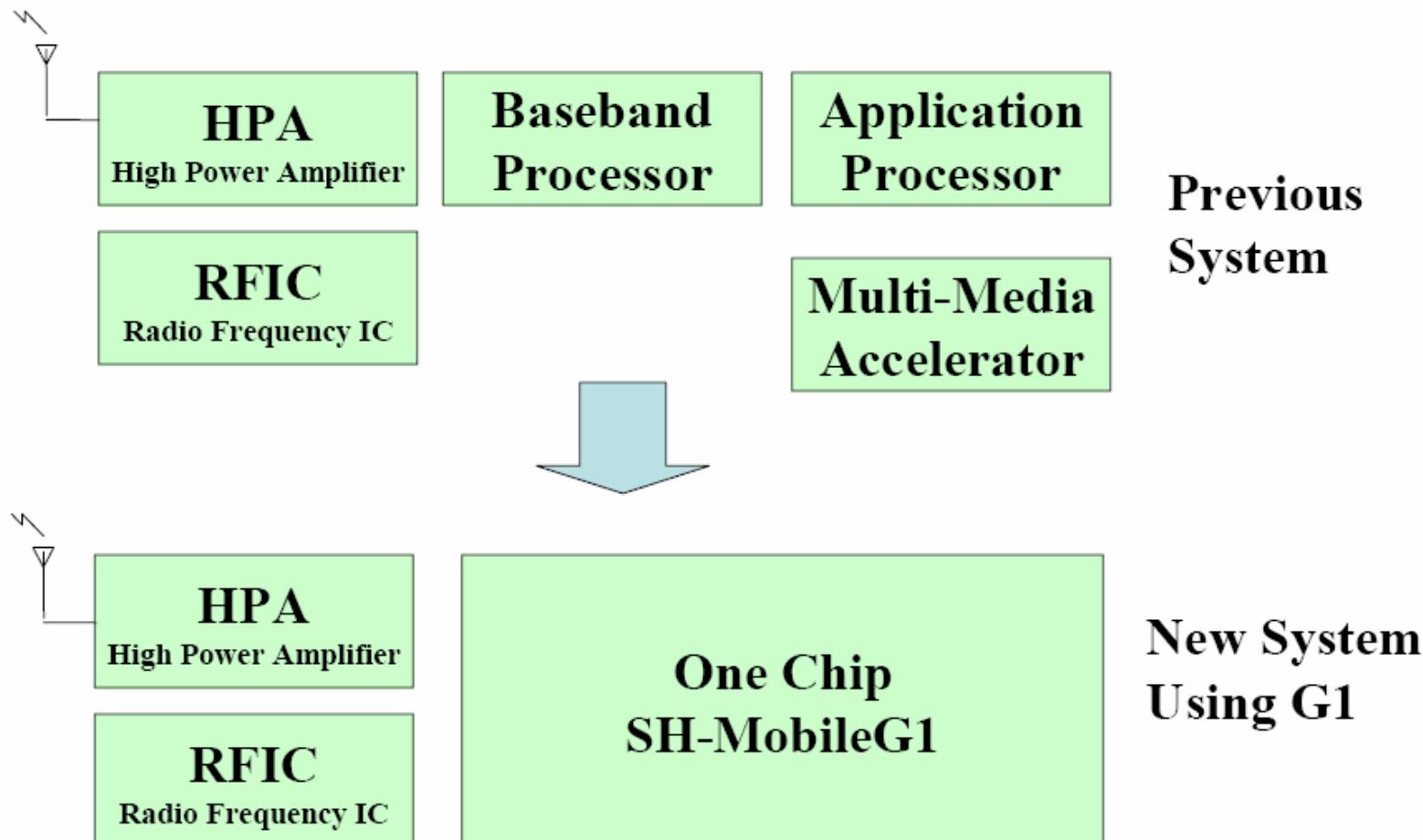
- MHS 80C51 as an example -

Features for Embedded Systems

- 8-bit CPU optimised for control applications
- Extensive Boolean processing capabilities
- 64 k Program Memory address space
- 64 k Data Memory address space
- 4 k bytes of on chip Program Memory
- 128 bytes of on chip data RAM
- 32 bi-directional and individually addressable I/O lines
- Two 16-bit timers/counters
- Full duplex UART
- 6 sources/5-vector interrupt structure with 2 priority levels
- On chip clock oscillators
- Very popular CPU with many different variations

Trend: multiprocessor systems-on-a-chip (MPSoCs)

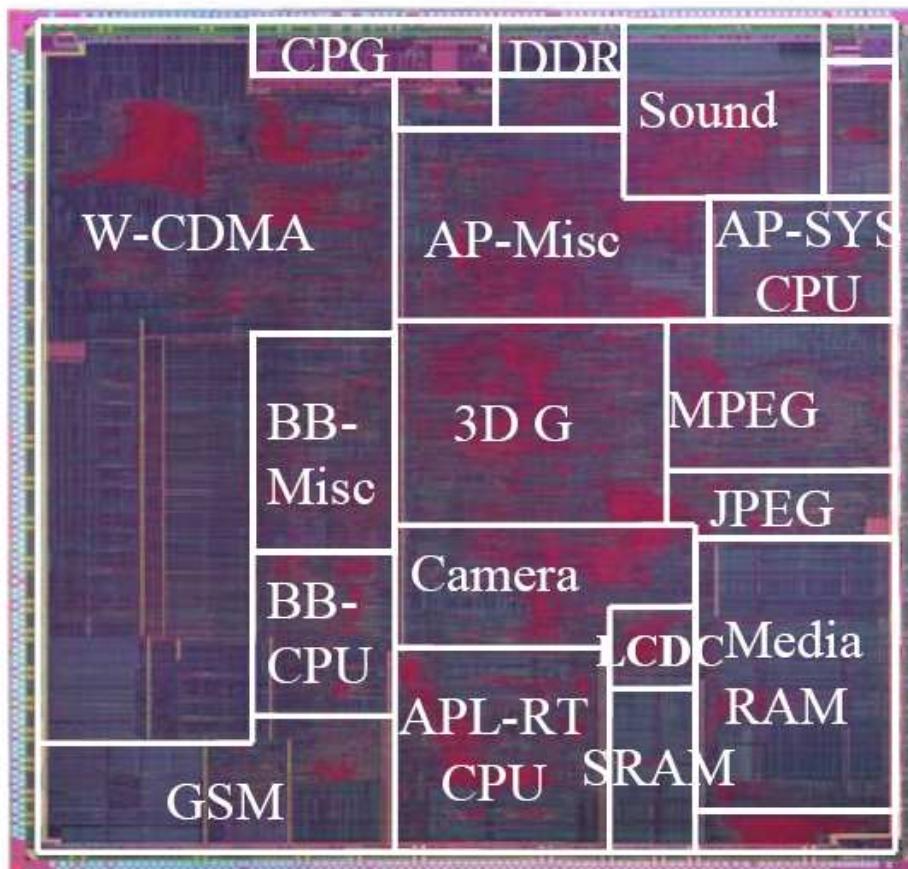
3G Multi-Media Cellular Phone System



<http://www.mpsoc-forum.org/2007/slides/Hattori.pdf>

Multiprocessor systems-on-a-chip (MPSoCs) (2)

SH-MobileG1: Chip Overview



Die size	11.15mm x 11.15mm
Process	90nm LP 8M(7Cu+1Al) CMOS dual-Vth
Supply voltage	1.2V(internal), 1.8/2.5/3.3V(I/O)
# of TRs, gate, memory	181M TRs, 13.5M Gate 20.2 Mbit mem

<http://www.mpsoc-forum.org/2007/slides/Hattori.pdf>

Multiprocessor systems-on-a-chip (MPSoCs) (3)

(2) Telephony (W-CDMA)



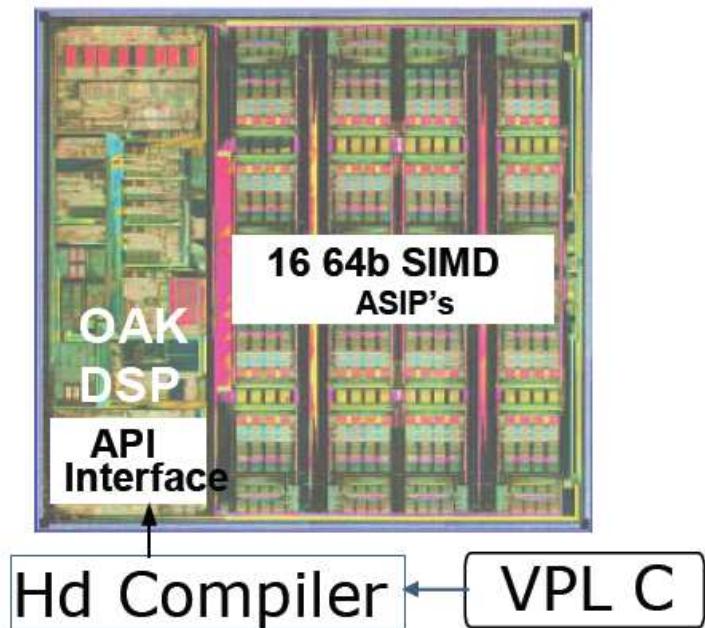
■ Power on
■ Power off

	Control	ON
Baseband part	W-CDMA	ON
	GSM	ON / OFF
Application part	System-domain	ON
	Realtime-domain	OFF
Measured Leakage Current (@ Room Temp, 1.2V)		407 µA

<http://www.mpsoc-forum.org/2007/slides/Hattori.pdf>

Multiprocessor systems-on-a-chip (MPSoCs) (4)

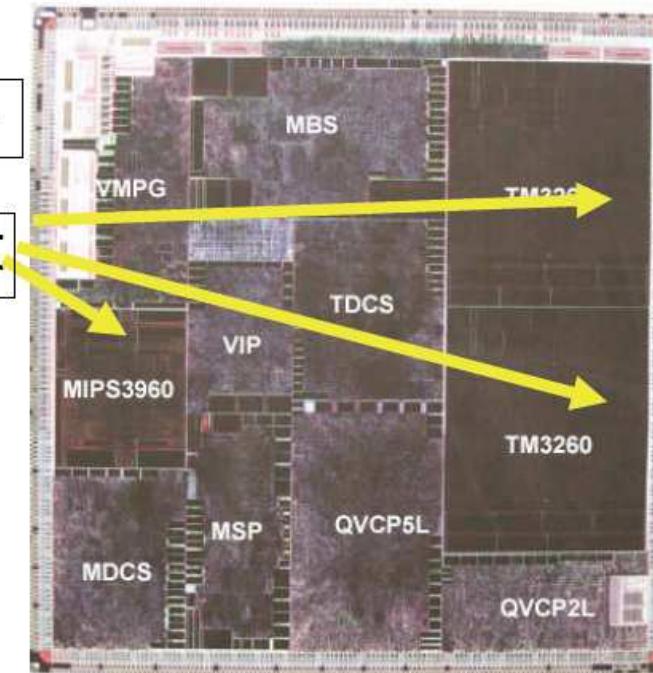
VIP for car mirrors
Infineon



200MHz , 0.76 Watt
100Gops @ 8b
25Gops @ 32b

~50% inherent power efficiency of silicon

Nexperia Digital Video Platform
NXP



1 MIPS, 2 Trimedia
60 coproc, 250 RAM's
266MHz, 1.5 watt 100 Gops

Embedded System Hardware

- Reconfigurable Hardware -

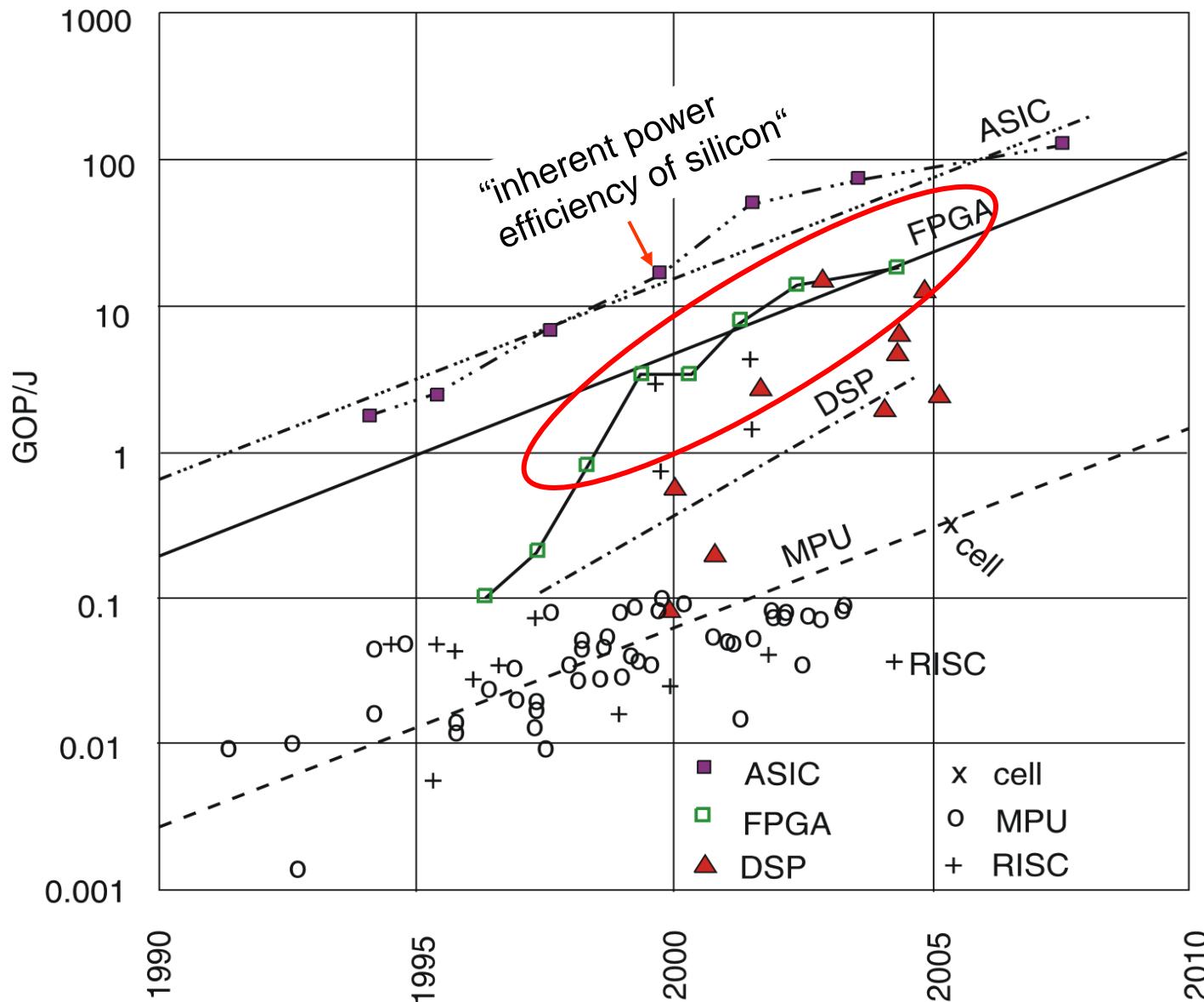
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2010年 06 月 12 日



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Energy Efficiency of FPGAs



© Hugo De Man,
IMEC, Philips, 2007

Reconfigurable Logic

Full custom chips may be too expensive, software too slow.
Combine the speed of HW with the flexibility of SW

- ☞ HW with programmable functions and interconnect.
- ☞ Use of configurable hardware;
common form: field programmable gate arrays (FPGAs)

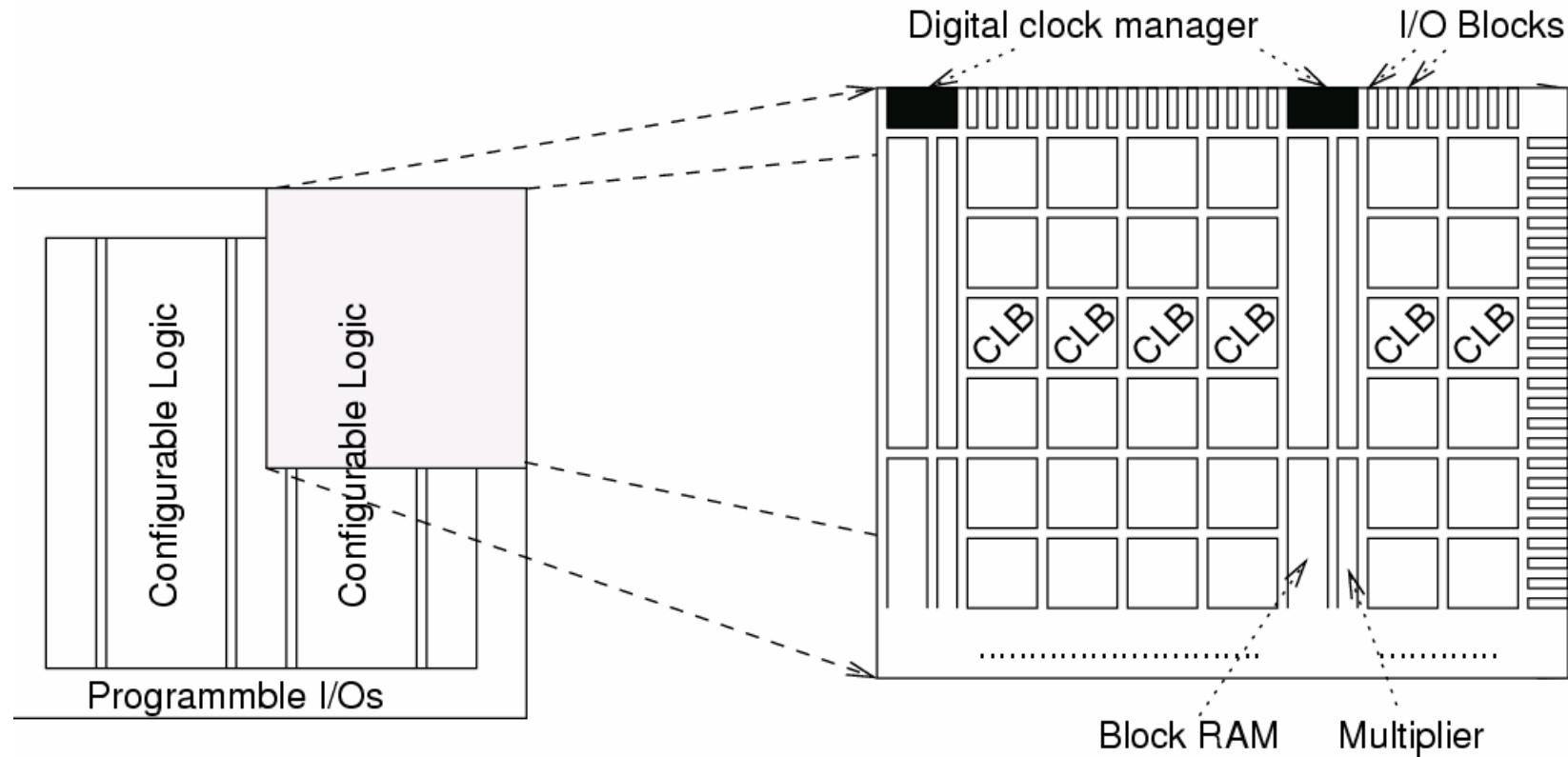
Applications: bit-oriented algorithms like

- encryption,
- fast “object recognition” (medical and military)
- Adapting mobile phones to different standards.

Very popular devices from

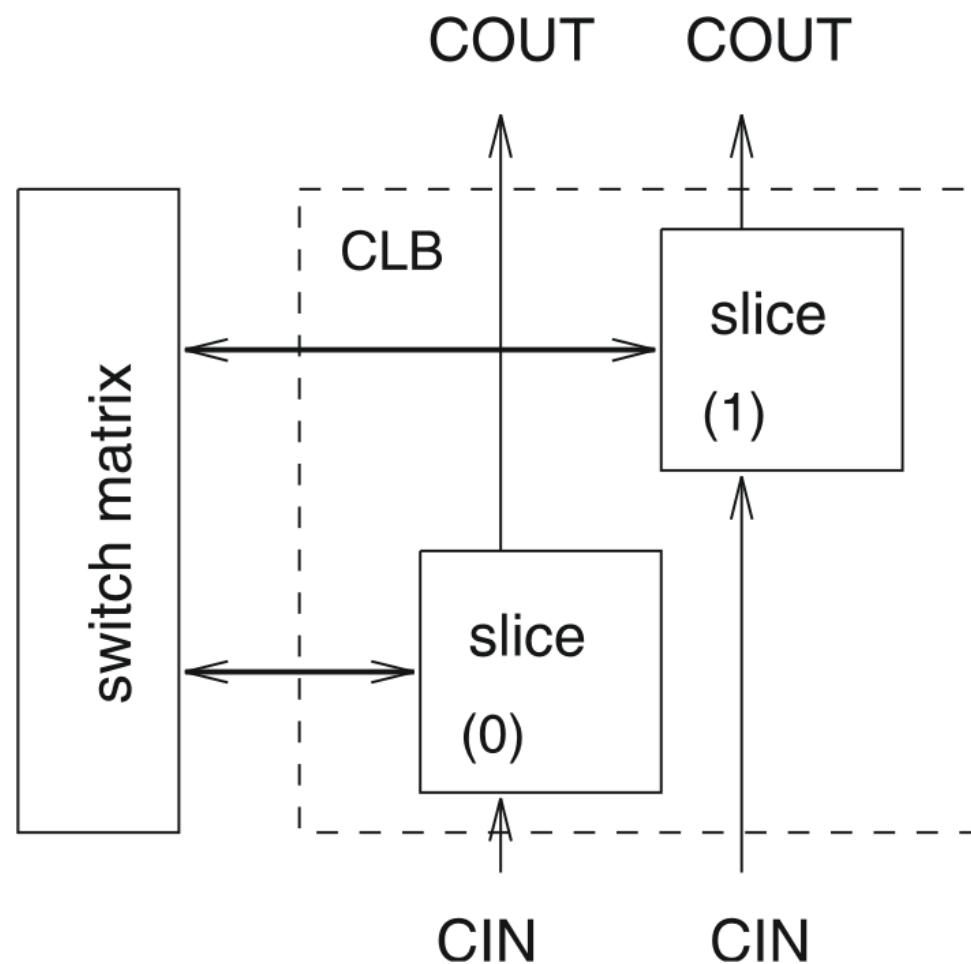
- XILINX (XILINX Vertex II are recent devices)
- Actel, Altera and others

Floor-plan of VIRTEX II FPGAs

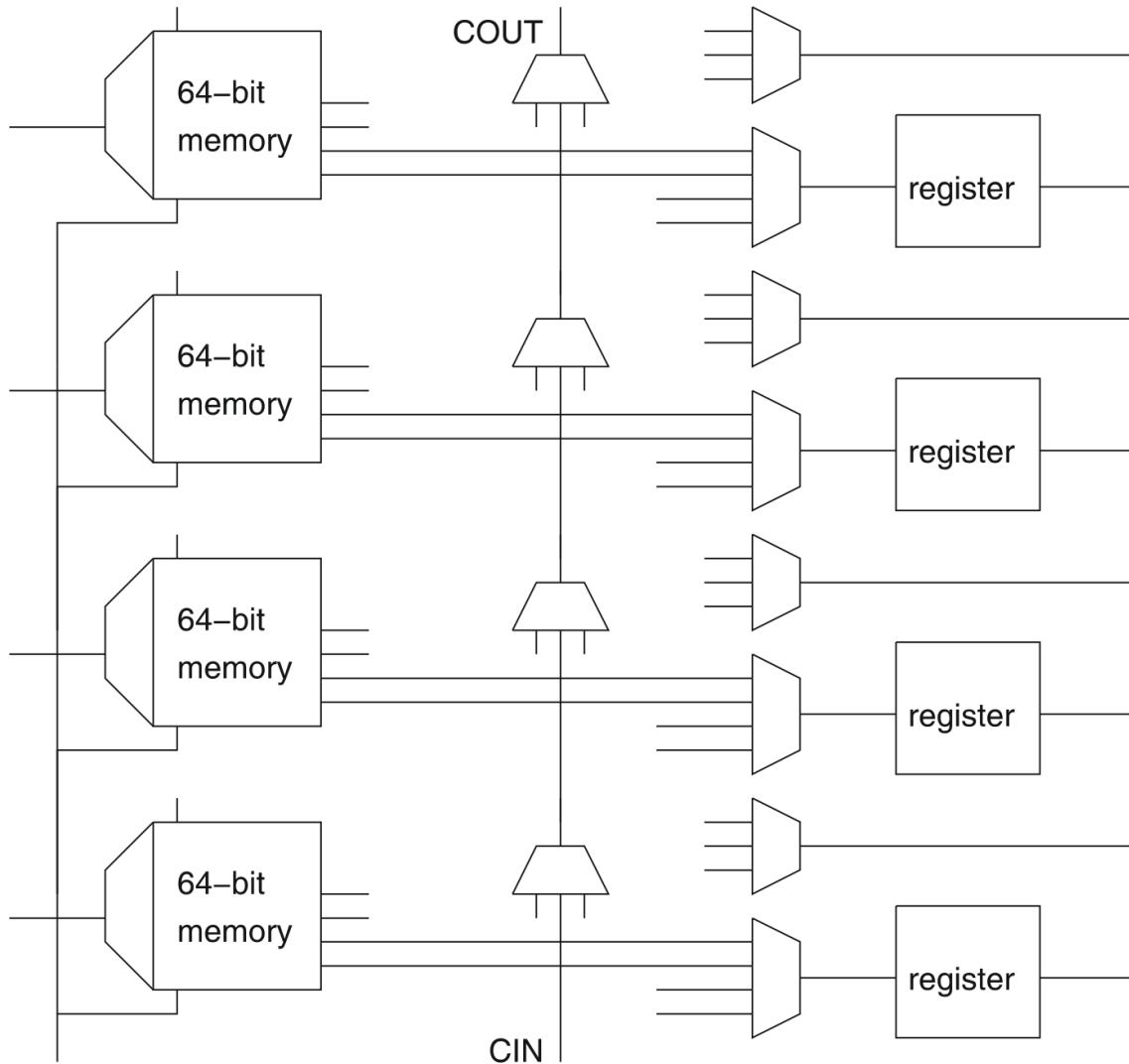


More recent: Virtex 5, but no floor-plan found for Virtex 5.

Virtex 5 Configurable Logic Block (CLB)



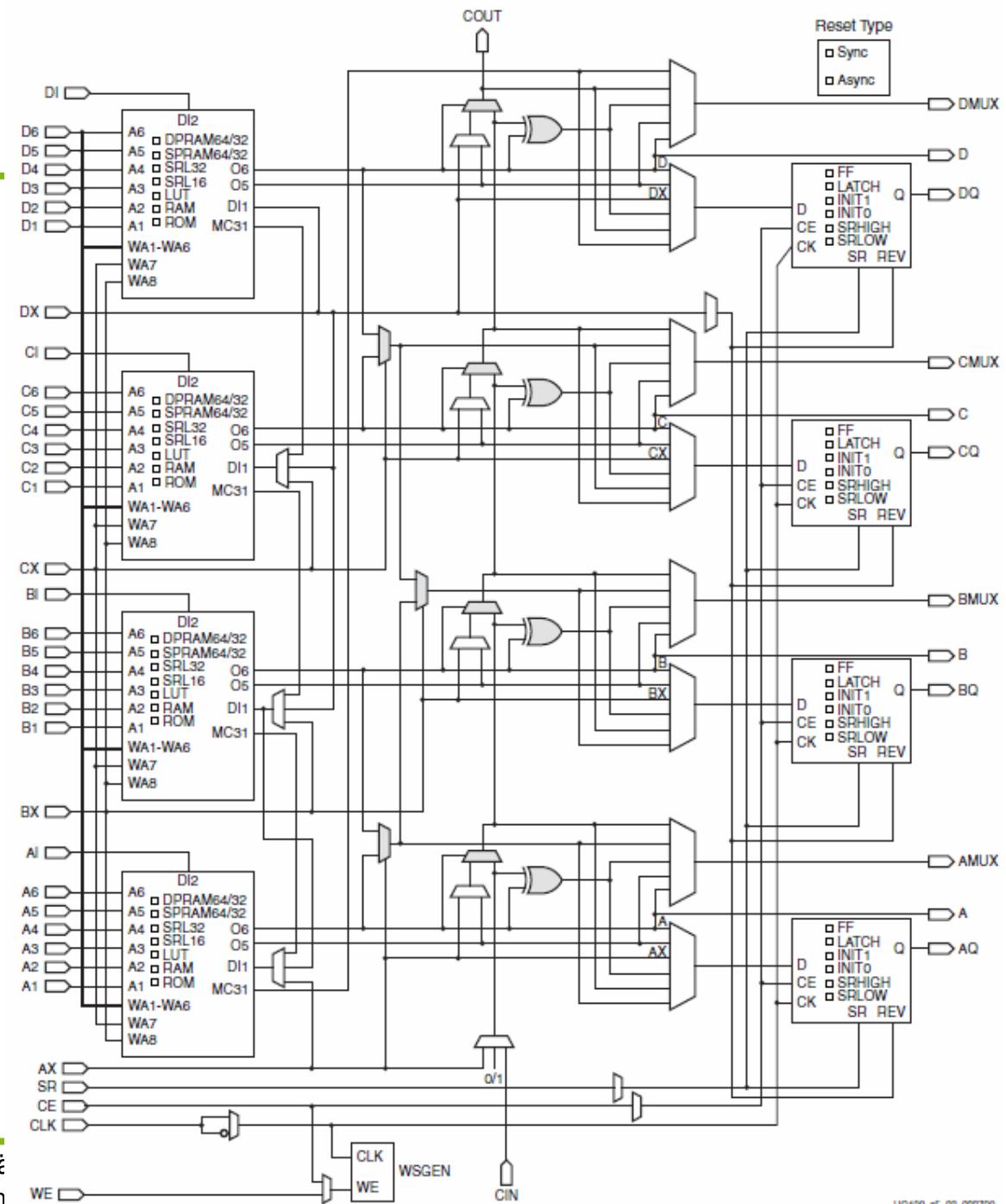
Virtex 5 Slice (simplified)



Memories typically used as look-up tables to implement any Boolean function of ≤ 6 variables.

Virtex 5 SliceM

SliceM supports using memories for storing data and as shift registers



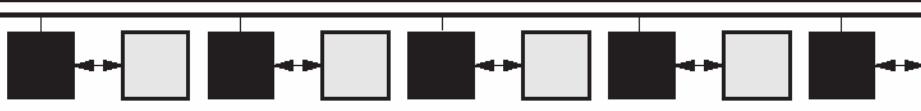
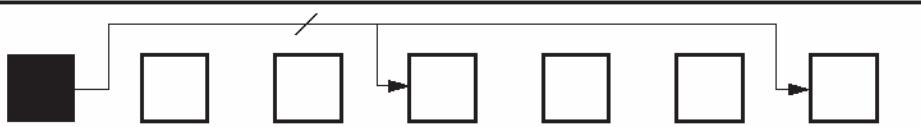
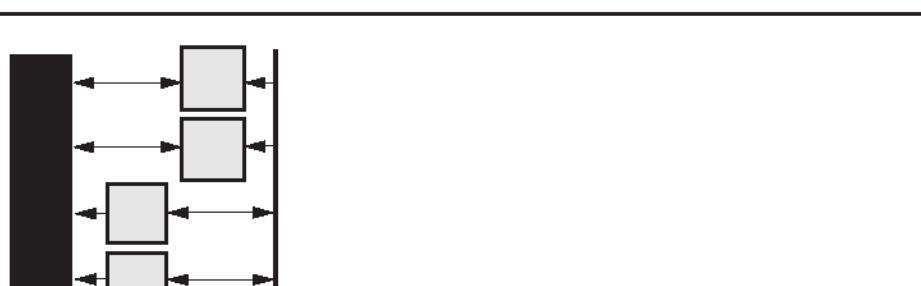
Resources available in Virtex 5 devices

Device	CLB Array Row x Column	Number of 6-Input LUTs	Maximum Distributed RAM (Kb)	Shift Register (Kb)	Number of Flip-Flops
XC5VLX20T	60 x 26	12,480	210	105	12,480
XC5VLX30	80 x 30	19,200	320	160	19,200
XC5VFX30T	80 x 38	20,480	380	190	20,480
XC5VLX30T	80 x 30	19,200	320	160	19,200
XC5VSX35T	80 x 34	21,760	520	260	21,760
XC5VLX50	120 x 30	28,800	480	240	28,800
XC5VLX50T	120 x 30	28,800	480	240	28,800
XC5VSX50T	120 x 34	32,640	780	390	32,640
XC5VFX70T	160 x 38	44,800	820	410	44,800
XC5VLX85	120 x 54	51,840	840	420	51,840
XC5VLX85T	120 x 54	51,840	840	420	51,840
XC5VSX95T	160 x 46	58,880	1,520	760	58,880
XC5VFX100T	160 x 56	64,000	1,240	620	64,000
XC5VLX110	160 x 54	69,120	1,120	560	69,120
XC5VLX110T	160 x 54	69,120	1,120	560	69,120
XC5VFX130T	200 x 56	81,920	1,580	790	81,920
XC5VTX150T	200 x 58	92,800	1,500	750	92,800
XC5VLX155	160 x 76	97,280	1,640	820	97,280
XC5VLX155T	160 x 76	97,280	1,640	820	97,280
XC5VFX200T	240 x 68	122,880	2,280	1140	122,880
XC5VLX220	160 x 108	138,240	2,280	1140	138,240
XC5VLX220T	160 x 108	138,240	2,280	1140	138,240
XC5VSX240T	240 x 78	149,760	4,200	2100	149,760
XC5VTX240T	240 x 78	149,760	2,400	1200	149,760
XC5VLX330	240 x 108	207,360	3,420	1710	207,360
XC5VLX330T	240 x 108	207,360	3,420	1710	207,360

[© and source: Xilinx Inc.:
Virtex 5 FPGA User
Guide, May, 2009
//www.xilinx.com]

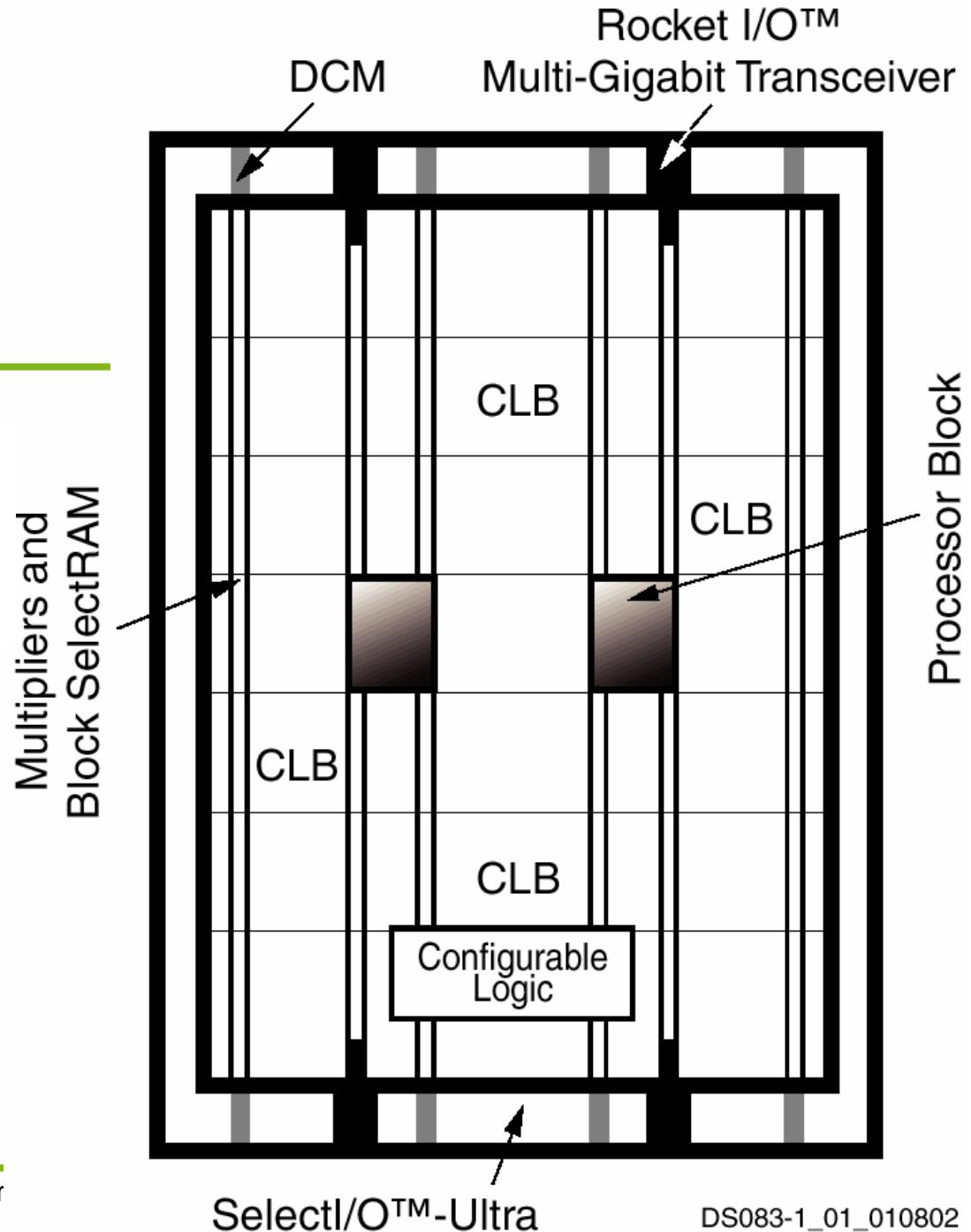
Interconnect for Virtex II

Hierarchical Routing Resources;
no routing found for Virtex 5.

24 Horizontal Long Lines 24 Vertical Long Lines	
120 Horizontal Hex Lines 120 Vertical Hex Lines	
40 Horizontal Double Lines 40 Vertical Double Lines	
16 Direct Connections (total in all four directions)	
8 Fast Connects	

Virtex II Pro Devices include up to 4 PowerPC processor cores

Virtex 5 Devices include
up to 2 PowerPC
processor cores



[© and source: Xilinx Inc.: Virtex-II Pro™ Platform
FPGAs: Functional Description, Sept. 2002,
[/www.xilinx.com](http://www.xilinx.com)]

Memory

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2009/11/22

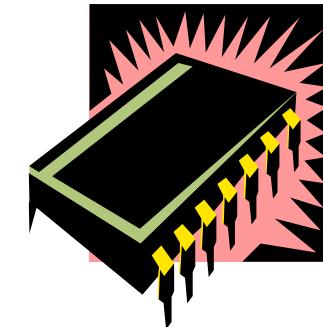


Memory

Memories?



Oops!
Memories!

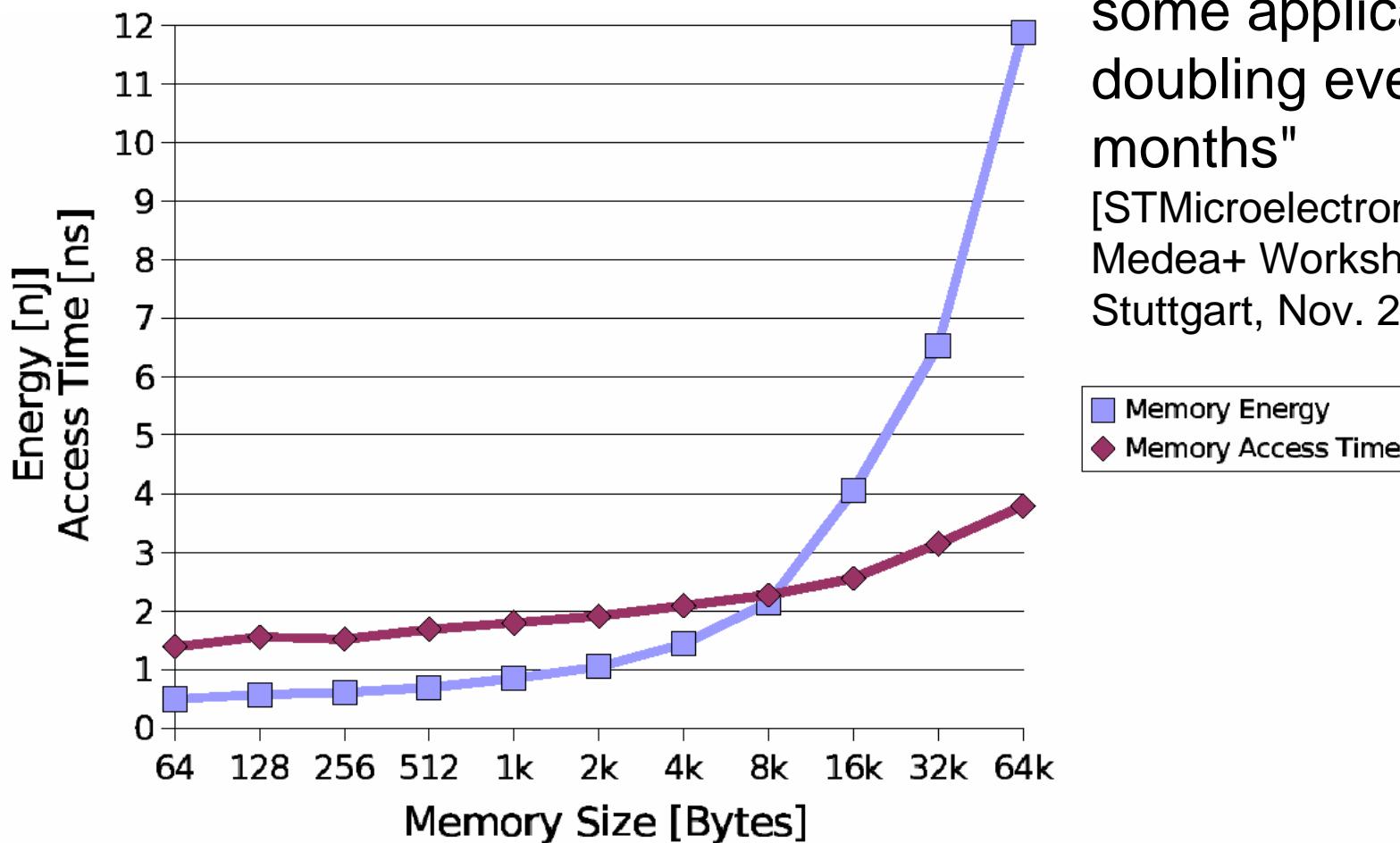


For the memory, efficiency is again a concern:

- speed (latency and throughput); predictable timing
- energy efficiency
- size
- cost
- other attributes (volatile vs. persistent, etc)

Access times and energy consumption increases with the size of the memory

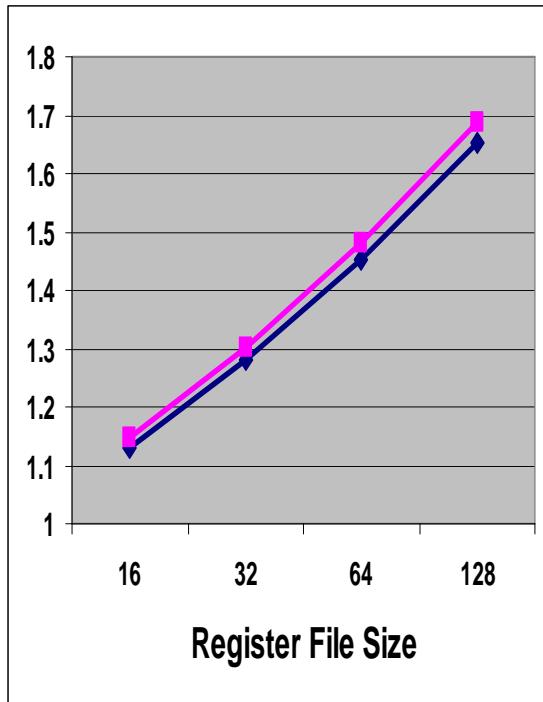
Example (CACTI Model):



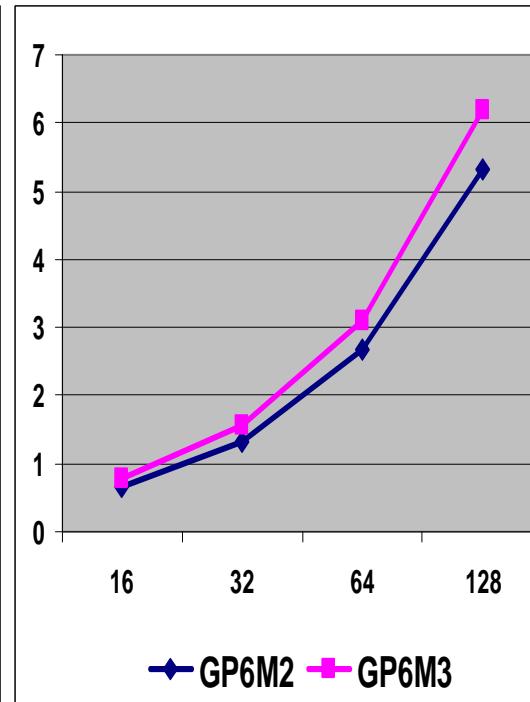
"Currently, the size of some applications is doubling every 10 months"
[STMicroelectronics,
Medea+ Workshop,
Stuttgart, Nov. 2003]

Access times and energy consumption for multi-ported register files

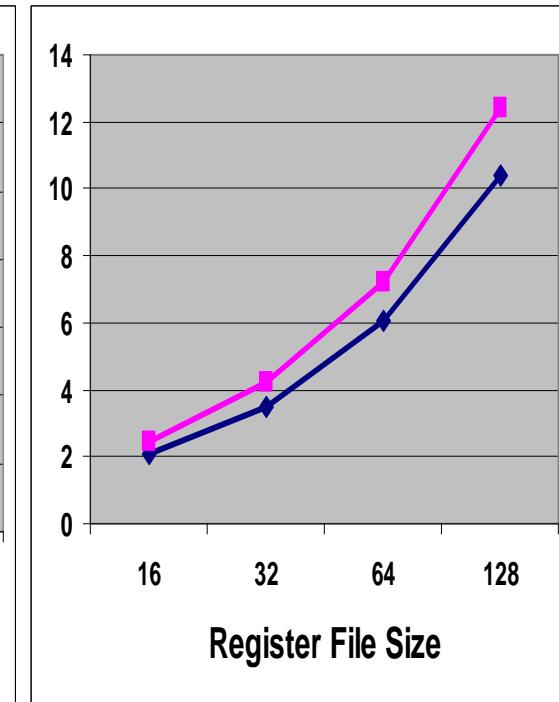
Cycle Time (ns)



Area ($\lambda^2 \times 10^6$)



Power (W)

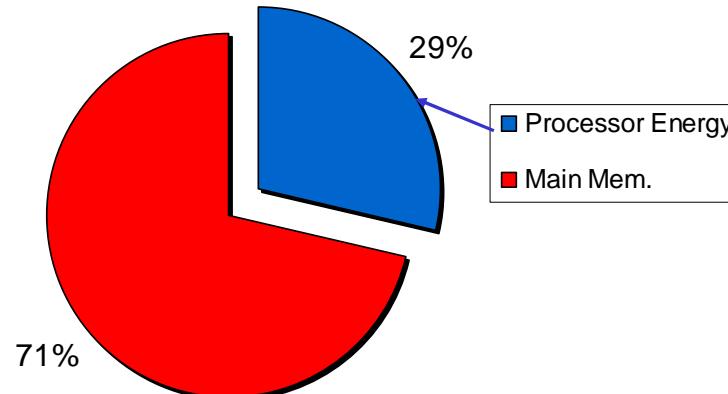


Rixner's et al. model [HPCA'00], Technology of 0.18 μ m

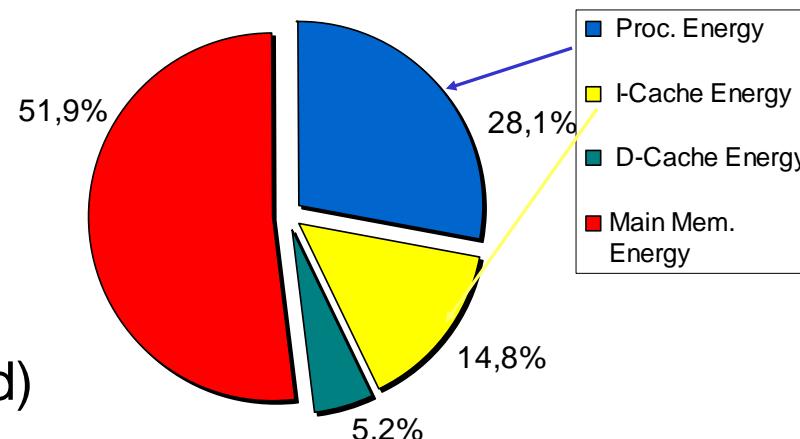
Source and © H. Valero, 2001

Memory system frequently consumes >50 % of the energy used for processing

Cache (\$)-less
monoprocessor



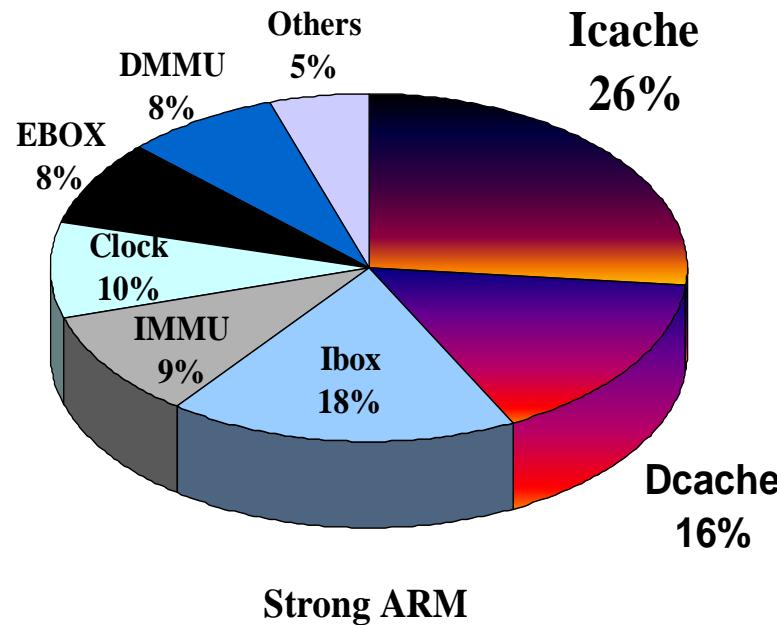
Multiprocessor with
cache (\$)



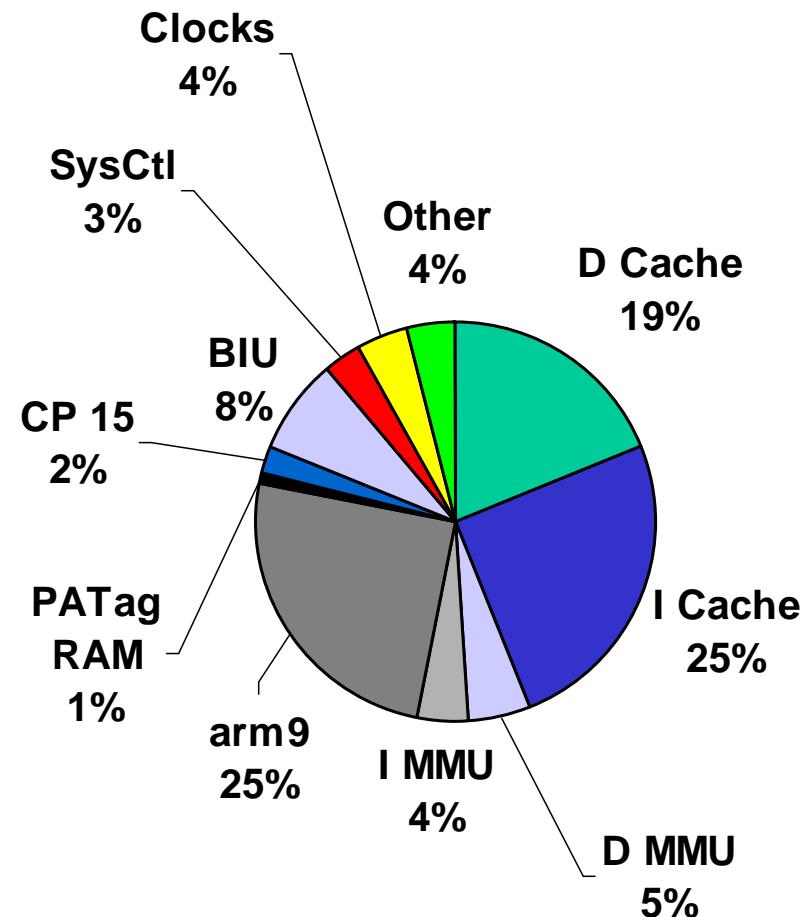
Average over 200 benchmarks
analyzed by Verma (U. Dortmund)

[M. Verma, P. Marwedel: Advanced Memory Optimization Techniques for Low-Power Embedded Processors, Springer, 2007]

Similar information according to other sources



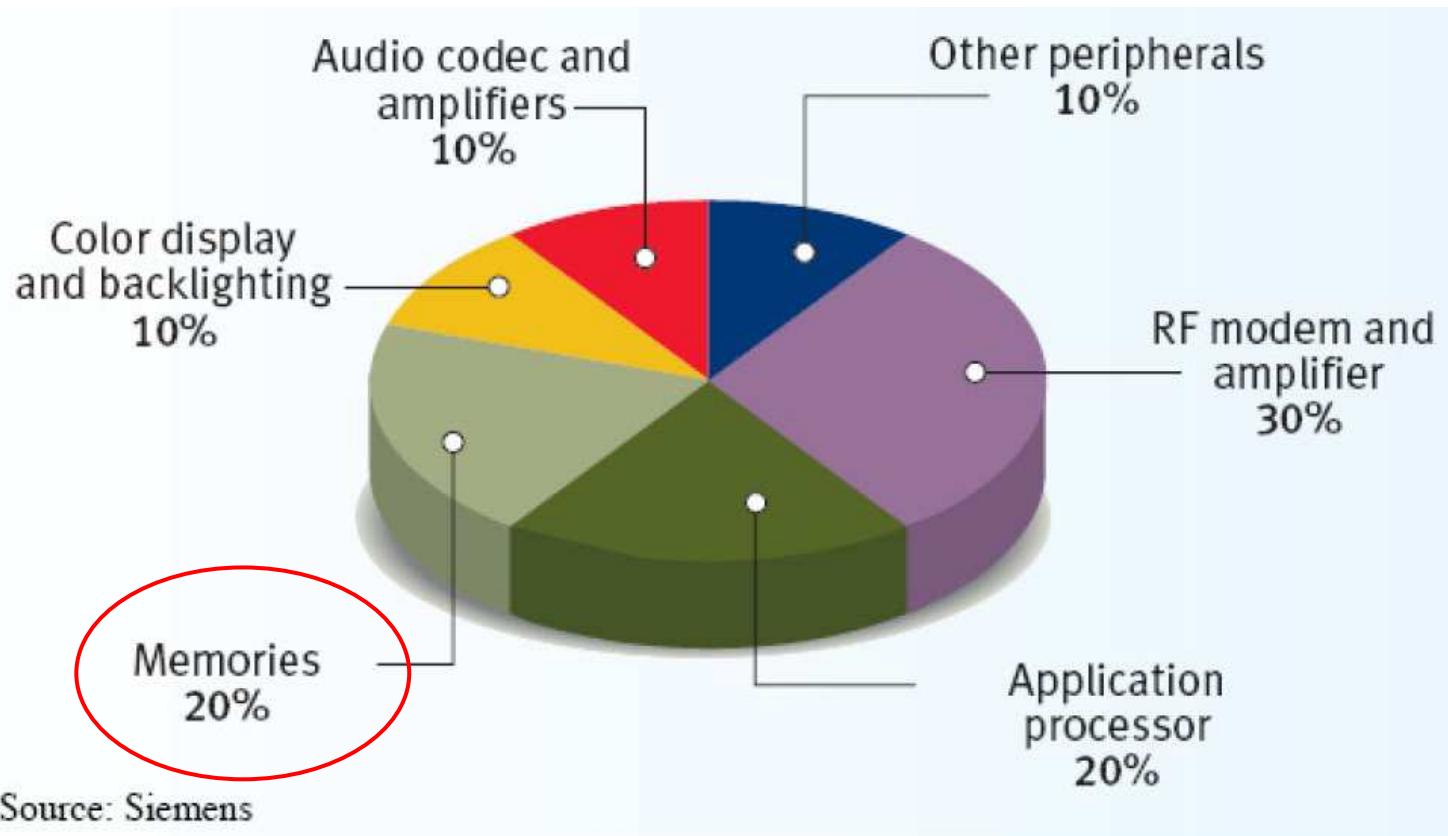
IEEE Journal of SSC
Nov. 96



[Based on slide by and ©: Osman S. Unsal, Israel Koren, C. Mani Krishna, Csaba Andras Moritz, U. of Massachusetts, Amherst, 2001]

[Segars 01 according to Vahid@ISSS01]

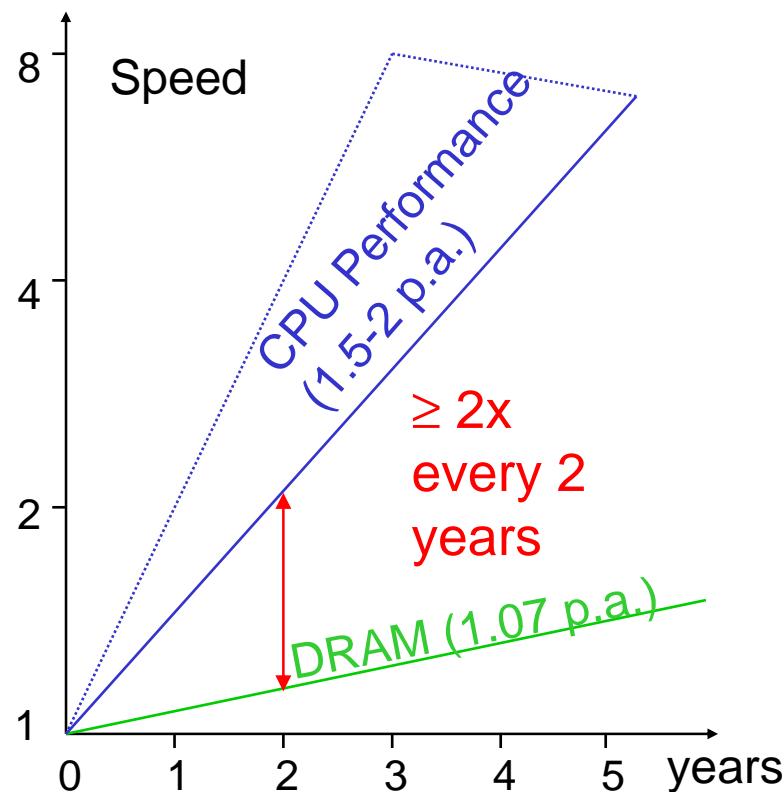
Energy consumption in mobile devices



[O. Vargas (Infineon Technologies): Minimum power consumption in mobile-phone memory subsystems; Pennwell Portable Design - September 2005;] Thanks to Thorsten Koch (Nokia/ Univ. Dortmund) for providing this source.

Trends for the Speeds

Speed gap between processor and main DRAM increases



Similar problems also for embedded systems & MPSoCs

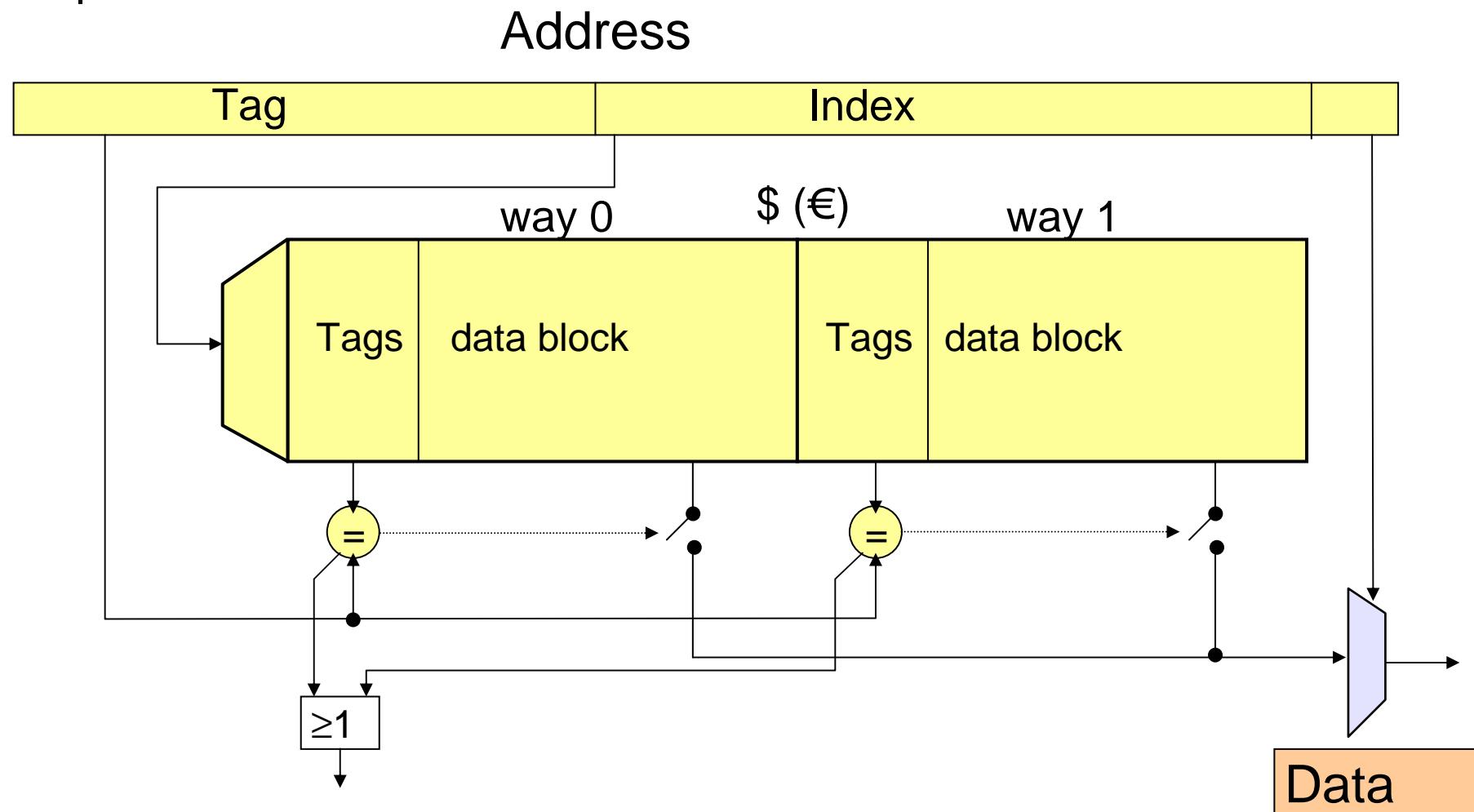
- ☞ In the future:
Memory access times $>>$ processor cycle times
- ☞ “Memory wall” problem



[P. Machanik: Approaches to Addressing the Memory Wall, TR Nov. 2002, U. Brisbane]

Set-associative cache n -way cache

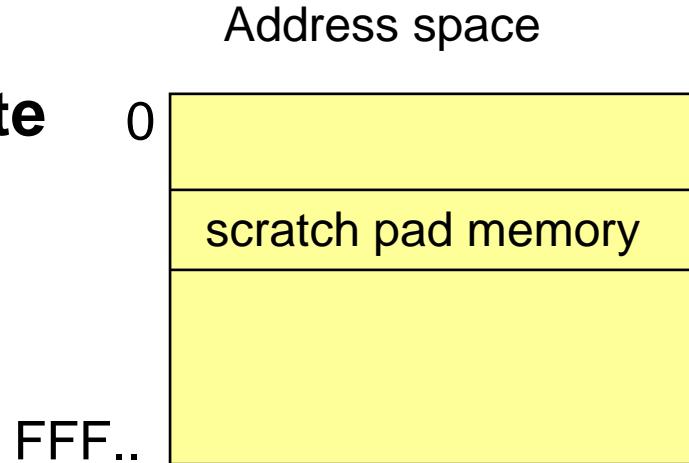
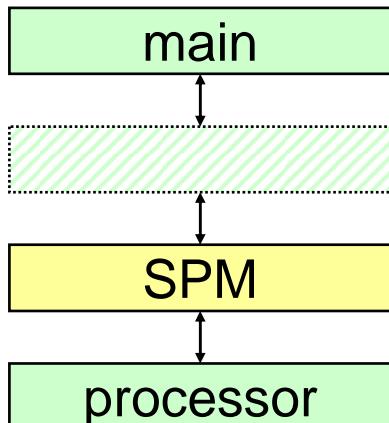
$|Set| = 2$



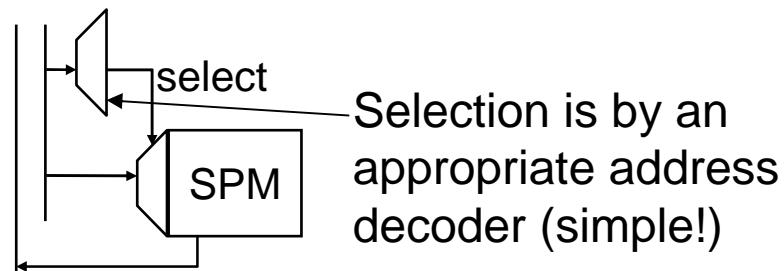
Hierarchical memories using scratch pad memories (SPM)

**SPM is a small,
physically separate
memory mapped
into the address
space**

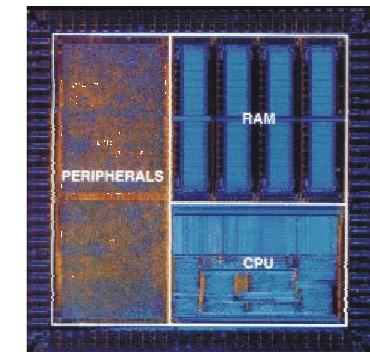
Hierarchy



no tag memory



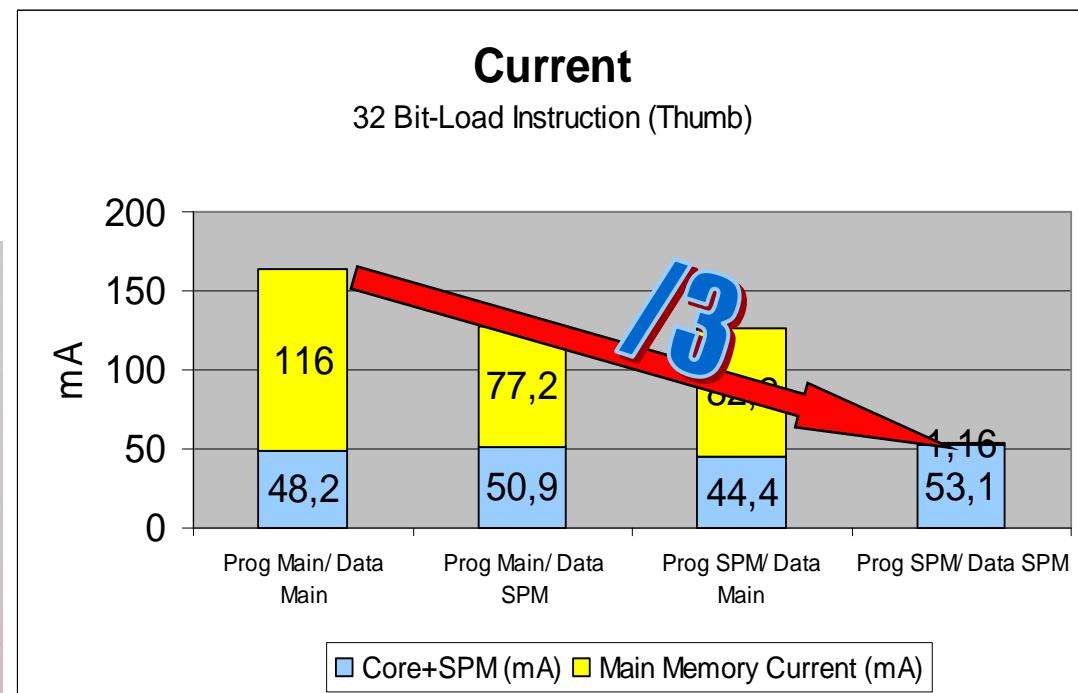
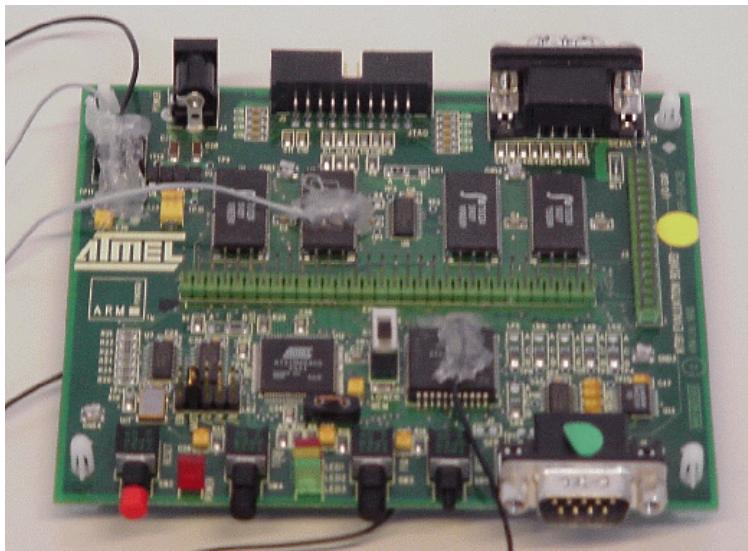
Example



ARM7TDMI
cores, well-
known for
low power
consumption

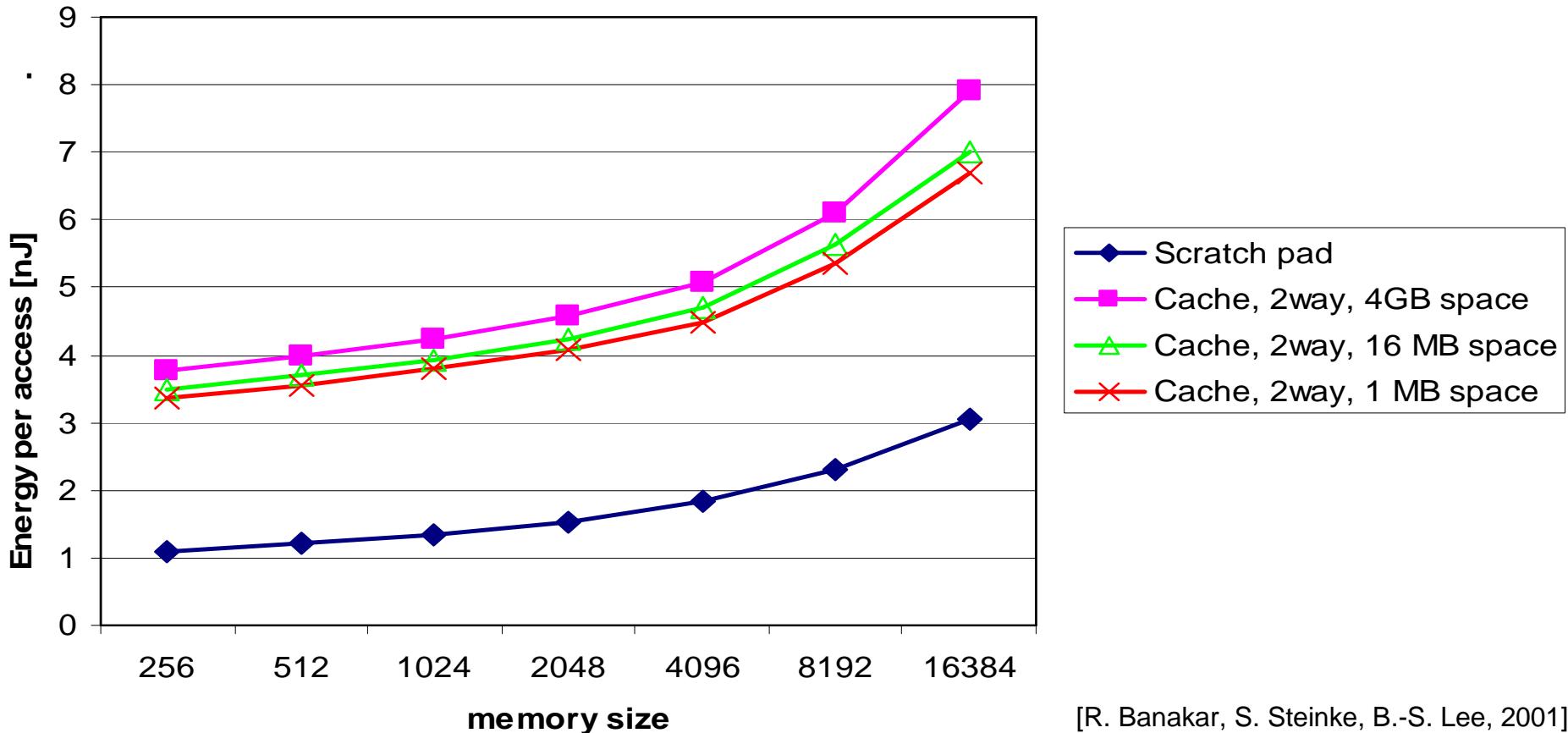
Comparison of currents using measurements

E.g.: ATMEL board with
ARM7TDMI and
ext. SRAM



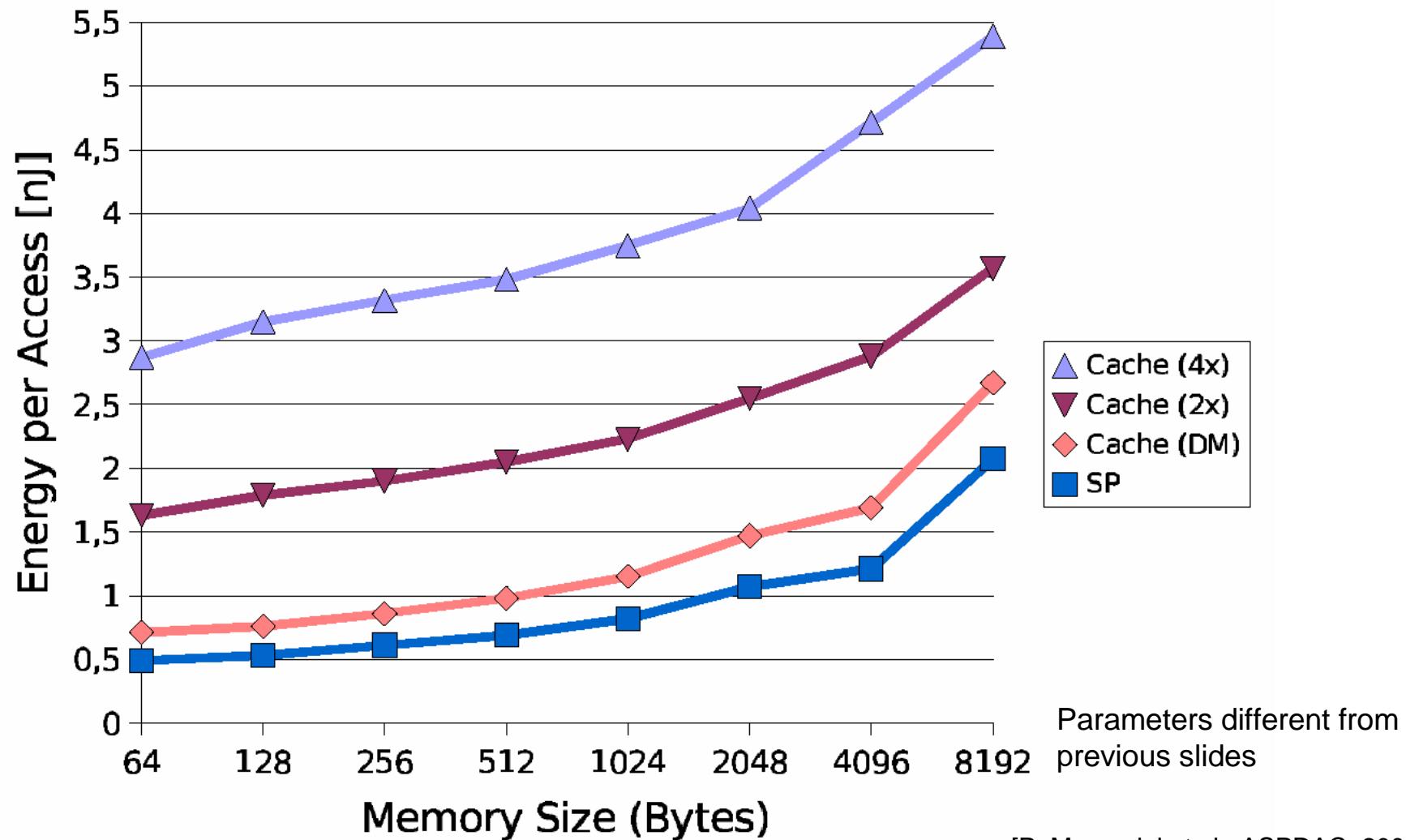
Why not just use a cache ?

2. Energy for parallel access of sets, in comparators, muxes.



[R. Banakar, S. Steinke, B.-S. Lee, 2001]

Influence of the associativity



Summary

- Processing
 - VLIW/EPIC processors
 - MPSoCs
- FPGAs
- Memories
 - “Small is beautiful”
(in terms of energy consumption, access times, size)